

STEPPER MOTOR CONTROLLER IC

 Check for Samples: [DRV8811](#)

FEATURES

- **Pulse Width Modulation (PWM) Microstepping Motor Driver**
 - Built-In Microstepping Indexer
 - Up to 2.5-A Current Per Winding
 - Three-Bit Winding Current Control Allows up to Eight Current Levels
 - Low MOSFET On-Resistance
- 8-V to 38-V Operating Supply Voltage Range
- Thermally Enhanced Surface Mount Package

APPLICATIONS

- Printers
- Scanners
- Office Automation Machines
- Gaming Machines
- Factory Automation
- Robotics

DESCRIPTION/ORDERING INFORMATION

The DRV8811 provides an integrated stepper motor driver solution for printers, scanners, and other automated equipment applications. The device has two H-bridge drivers, as well as microstepping indexer logic to control a stepper motor.

The output driver block for each consists of N-channel power MOSFETs configured as full H-bridges to drive the motor windings.

A simple step/direction interface allows easy interfacing to controller circuits. Pins allow configuration of the motor in full-step, half-step, quarter-step, or eighth-step modes. Decay mode and PWM off time are programmable.

Internal shutdown functions are provided for over current protection, short circuit protection, under-voltage lockout and overtemperature.

The DRV8811 is packaged in a PowerPAD™ 28-pin HTSSOP package with thermal pad (Eco-friendly: RoHS and no Sb/Br).

ORDERING INFORMATION⁽¹⁾

T _A	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PowerPAD™ (HTSSOP) – PWP	Reel of 2000	DRV8811PWPR	DRV8811
		Tube of 50	DRV8811PWP	

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

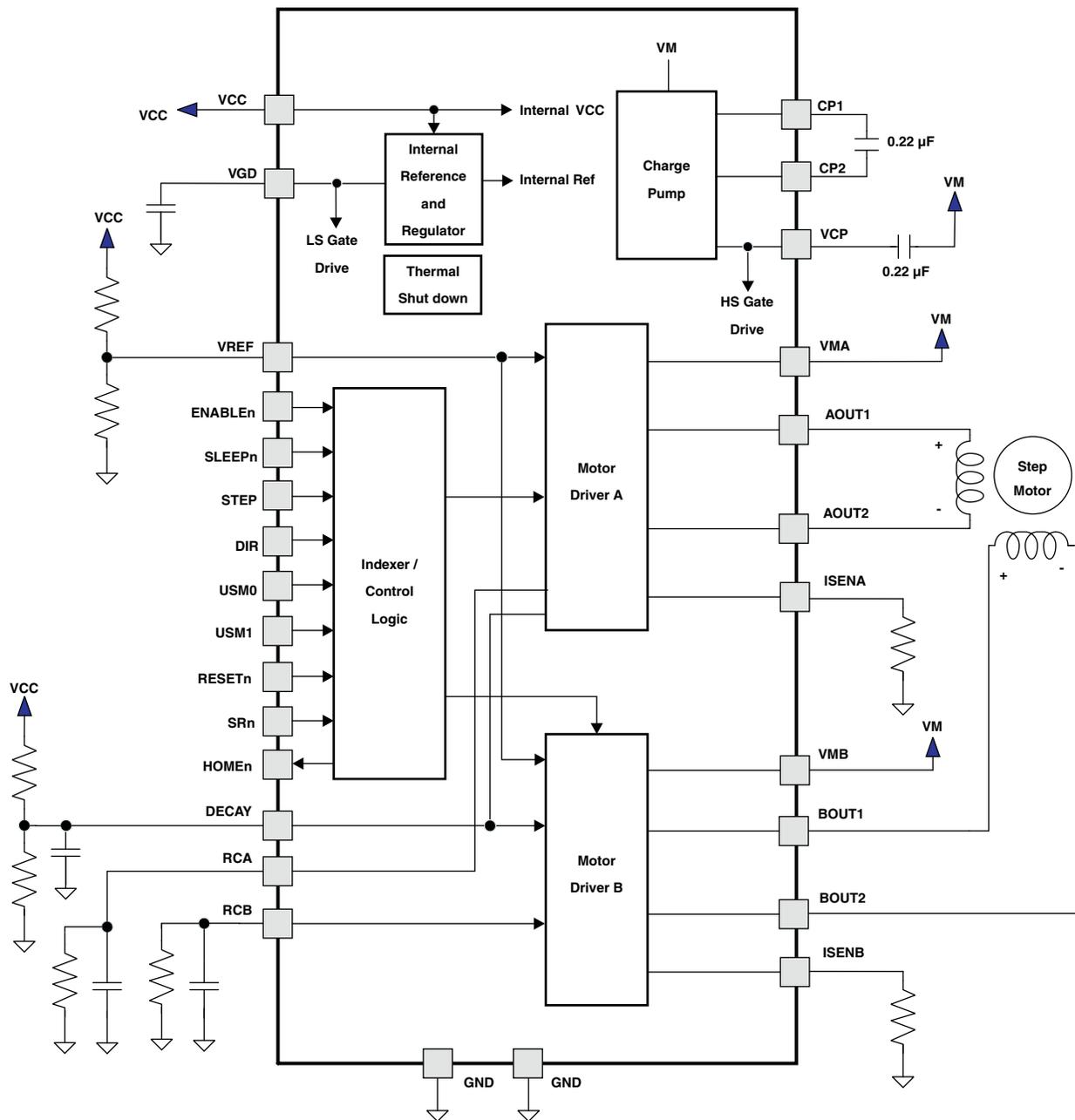
(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



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PowerPAD is a trademark of Texas Instruments.

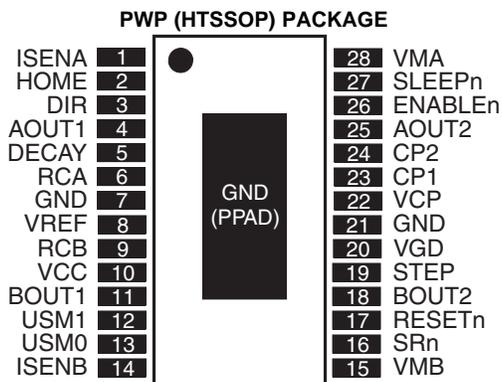
FUNCTIONAL BLOCK DIAGRAM



TERMINAL FUNCTIONS

NAME	NO.	I/O ⁽¹⁾	DESCRIPTION	EXTERNAL COMPONENTS OR CONNECTIONS
POWER AND GROUND				
GND	7, 21	-	Device ground	
VMA	28	-	Bridge A power supply	Connect to motor supply (8 V to 38 V). Both pins must be connected to same supply.
VMB	15	-	Bridge B power supply	Connect to motor supply (8 V to 38 V). Both pins must be connected to same supply.
VCC	10	-	Logic supply voltage	Connect to 3-V to 5-V logic supply. Bypass to GND with a 0.1- μ F ceramic capacitor
CP1	23	IO	Charge pump flying capacitor	Connect a 0.22- μ F capacitor between CP1 and CP2
CP2	24	IO	Charge pump flying capacitor	Connect a 0.22- μ F capacitor between CP1 and CP2
VCP	22	IO	High-side gate drive voltage	Connect a 0.22- μ F ceramic capacitor to V_M
VGD	20	IO	Low-side gate drive voltage	Bypass to GND with a 0.22- μ F ceramic capacitor
CONTROL				
ENABLEn	26	I	Enable input	Logic high to disable device outputs, logic low to enable outputs
SLEEPn	27	I	Sleep mode input	Logic high to enable device, logic low to enter low-power sleep mode
DECAY	5	I	Decay mode select	Voltage applied sets decay mode - see motor driver description for details. Bypass to GND with a 0.1- μ F ceramic capacitor
STEP	19	I	Step input	Rising edge causes the indexer to move one step
DIR	3	I	Direction input	Level sets the direction of stepping
USM0	13	I	Microstep mode 0	USM0 and USM1 set the step mode - full step, half step, quarter step, or eight microsteps/step
USM1	12	I	Microstep mode 1	USM0 and USM1 set the step mode - full step, half step, quarter step, or eight microsteps/step
RESETn	17	I	Reset input	Active-low reset input initializes the indexer logic and disables the H-bridge outputs
SRn	16	I	Sync. Rect. enable input	When active low, synchronous rectification is enabled
VREF	8	I	Current set reference input	Reference voltage for winding current set
RCA	6	I	Bridge A blanking and off time adjust	Connect a parallel resistor and capacitor to GND - see motor driver description for details
RCB	9	I	Bridge B blanking and off time adjust	Connect a parallel resistor and capacitor to GND - see motor driver description for details
ISENA	1	-	Bridge A ground / Isense	Connect to current sense resistor for bridge A
ISENB	14	-	Bridge B ground / Isense	Connect to current sense resistor for bridge B
OUTPUTS				
AOUT1	4	O	Bridge A output 1	Connect to bipolar stepper motor winding A
AOUT2	25	O	Bridge A output 2	Positive current is AOUT1 \rightarrow AOUT2
BOUT1	11	O	Bridge B output 1	Connect to bipolar stepper motor winding B
BOUT2	18	O	Bridge B output 2	Positive current is BOUT1 \rightarrow BOUT2
HOMEn	2	O	Home position	Logic low when at home state of step table, logic high at other states

(1) Directions: I = input, O = output, OZ = 3-state output, OD = open-drain output, IO = input/output



ABSOLUTE MAXIMUM RATINGS (1) (2) (3)

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{MX}	Power supply voltage range	-0.3	40	V
V_{CC}	Power supply voltage range	-0.3	7	V
	Digital pin voltage range	-0.5	V_{CC}	V
V_{REF}	Input voltage range	-0.3 V	V_{CC}	V
	ISENSEx pin voltage range	-0.3	0.5	V
$I_{O(peak)}$	Peak motor drive output current, $t < 1 \mu s$		6	A
I_O	Continuous motor drive output current		± 2.5	A
P_D	Continuous total power dissipation	See Dissipation Ratings Table		
T_J	Operating virtual junction temperature range	-40	150	°C
T_A	Operating ambient temperature range	-40	85	°C
T_{stg}	Storage temperature range	-60	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to network ground terminal.
- (3) Power dissipation and thermal limits must be observed.

DISSIPATION RATINGS

BOARD	PACKAGE	$R_{\theta JA}$	DERATING FACTOR ABOVE $T_A = 25^\circ C$	$T_A < 25^\circ C$	$T_A = 70^\circ C$	$T_A = 85^\circ C$
Low-K ⁽¹⁾	PWP	67.5 °C/W	14.8 mW/°C	1.85 W	1.18 W	0.96 W
Low-K ⁽²⁾	PWP	39.5 °C/W	25.3 mW/°C	3.16 W	2.02 W	1.64 W
High-K ⁽³⁾	PWP	33.5 °C/W	29.8 mW/°C	3.73 W	2.38 W	1.94 W
High-K ⁽⁴⁾	PWP	28 °C/W	35.7 mW/°C	4.46 W	2.85 W	2.32 W

- (1) The JEDEC Low-K board used to derive this data was a 76 mm x 114 mm, 2-layer, 1.6 mm thick PCB with no backside copper.
- (2) The JEDEC Low-K board used to derive this data was a 76 mm x 114 mm, 2-layer, 1.6 mm thick PCB with 25 cm² 2-oz copper on backside.
- (3) The JEDEC High-K board used to derive this data was a 76 mm x 114 mm, 4-layer, 1.6 mm thick PCB with no backside copper and solid 1 oz. internal ground plane.
- (4) The JEDEC High-K board used to derive this data was a 76 mm x 114 mm, 4-layer, 1.6 mm thick PCB with 25 cm² 1-oz copper on backside and solid 1 oz. internal ground plane.

RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V_M	Motor power supply voltage range ⁽¹⁾	8		38	V
V_{CC}	Logic power supply voltage range	3		5.5	V
V_{REF}	VREF input voltage			V_{CC}	V

(1) All V_M pins must be connected to the same supply voltage.

ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

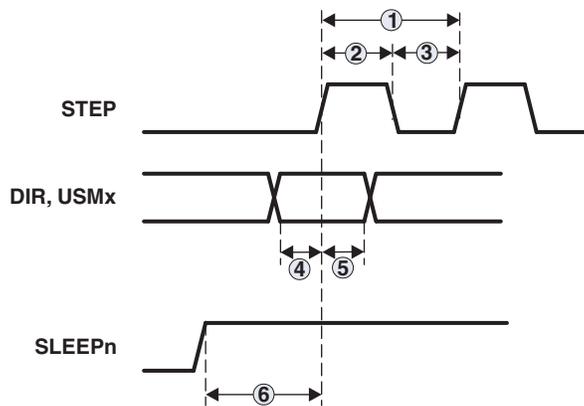
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Power Supplies						
I_{VM}	V_M operating supply current	$V_M = 35\text{ V}$, $f_{PWM} < 50\text{ KHz}$		4.5	8	mA
I_{VCC}	V_{CC} operating supply current	$f_{PWM} < 50\text{ KHz}$		0.4	4	mA
I_{VMQ}	V_M sleep mode supply current	$V_M = 35\text{ V}$		12	20	μA
I_{VCCQ}	V_{CC} sleep mode supply current			5	20	μA
V_{UVLO}	V_M undervoltage lockout voltage	V_M rising		6.7	8	V
	V_{CC} undervoltage lockout voltage	V_{CC} rising		2.71	2.95	
VREF Input/Current Control Accuracy						
I_{REF}	VREF input current	$V_{REF} = 3.3\text{ V}$	-3		3	μA
ΔI_{CHOP}	Chopping current accuracy	$V_{REF} = 2.0\text{ V}$, 70% to 100% current	-5		5	%
		$V_{REF} = 2.0\text{ V}$, 20% to 56% current	-10		10	%
Logic-Level Inputs						
V_{IL}	Input low voltage				$0.3 \times V_{CC}$	V
V_{IH}	Input high voltage		$0.7 \times V_{CC}$			V
I_{IL}	Input low current	$V_{IN} = 0.3 \times V_{CC}$	-20		20	μA
I_{IH}	Input high current	$V_{IN} = 0.3 \times V_{CC}$	-20		20	μA
HOMEn Output						
V_{OL}	Output low voltage	$I_O = 200\ \mu\text{A}$			$0.3 \times V_{CC}$	V
V_{OH}	Output high voltage	$I_O = -200\ \mu\text{A}$	$0.7 \times V_{CC}$			V
Decay Input						
V_{IL}	Input low threshold voltage	For fast decay mode		$0.21 \times V_{CC}$		V
V_{IH}	Input high threshold voltage	For slow decay mode		$0.6 \times V_{CC}$		V
H-Bridge FETS						
$R_{ds(on)}$	HS FET on resistance	$V_M = 24\text{ V}$, $I_O = 2.5\text{ A}$, $T_J = 25^\circ\text{C}$		0.50		Ω
		$V_M = 24\text{ V}$, $I_O = 2.5\text{ A}$, $T_J = 85^\circ\text{C}$		0.60	0.75	
$R_{ds(on)}$	LS FET on resistance	$V_M = 24\text{ V}$, $I_O = 2.5\text{ A}$, $T_J = 25^\circ\text{C}$		0.50		Ω
		$V_M = 24\text{ V}$, $I_O = 2.5\text{ A}$, $T_J = 85^\circ\text{C}$		0.60	0.75	
I_{OFF}			-20		20	μA
Motor Driver						
t_{OFF}	Off time	$R_x = 56\text{ k}\Omega$, $C_x = 680\text{ pF}$	30	38	46	μs
t_{BLANK}	Current sense blanking time	$R_x = 56\text{ k}\Omega$, $C_x = 680\text{ pF}$	700	950	1200	ns
t_{DT}	Dead time ⁽¹⁾	$SR_n = 0$	100	475	800	ns
Protection Circuits						
I_{OCP}	Overcurrent protection trip level		2.5	4.5	6.5	A
t_{TSD}	Thermal shutdown temperature ⁽¹⁾	Die temperature	150	160	180	$^\circ\text{C}$

(1) Not tested in production - guaranteed by design.

TIMING REQUIREMENTS

over operating free-air temperature range (unless otherwise noted)

PARAMETER		MIN	MAX	UNIT
f_{STEP}	Step frequency		500	kHz
$t_{WH(STEP)}$	Pulse duration, STEP high	1		μ s
$t_{WL(STEP)}$	Pulse duration, STEP low	1		μ s
$t_{SU(STEP)}$	Setup time, command to STEP rising	200		ns
$t_{H(STEP)}$	Hold time, command to STEP rising	200		ns
t_{WAKE}	Wakeup time, SLEEPn inactive to STEP	1		ms



FUNCTIONAL DESCRIPTION

PWM H-Bridge Drivers

DRV8811 contains two H-bridge motor drivers with current-control PWM circuitry, and a microstepping indexer. A block diagram of the motor control circuitry is shown below.

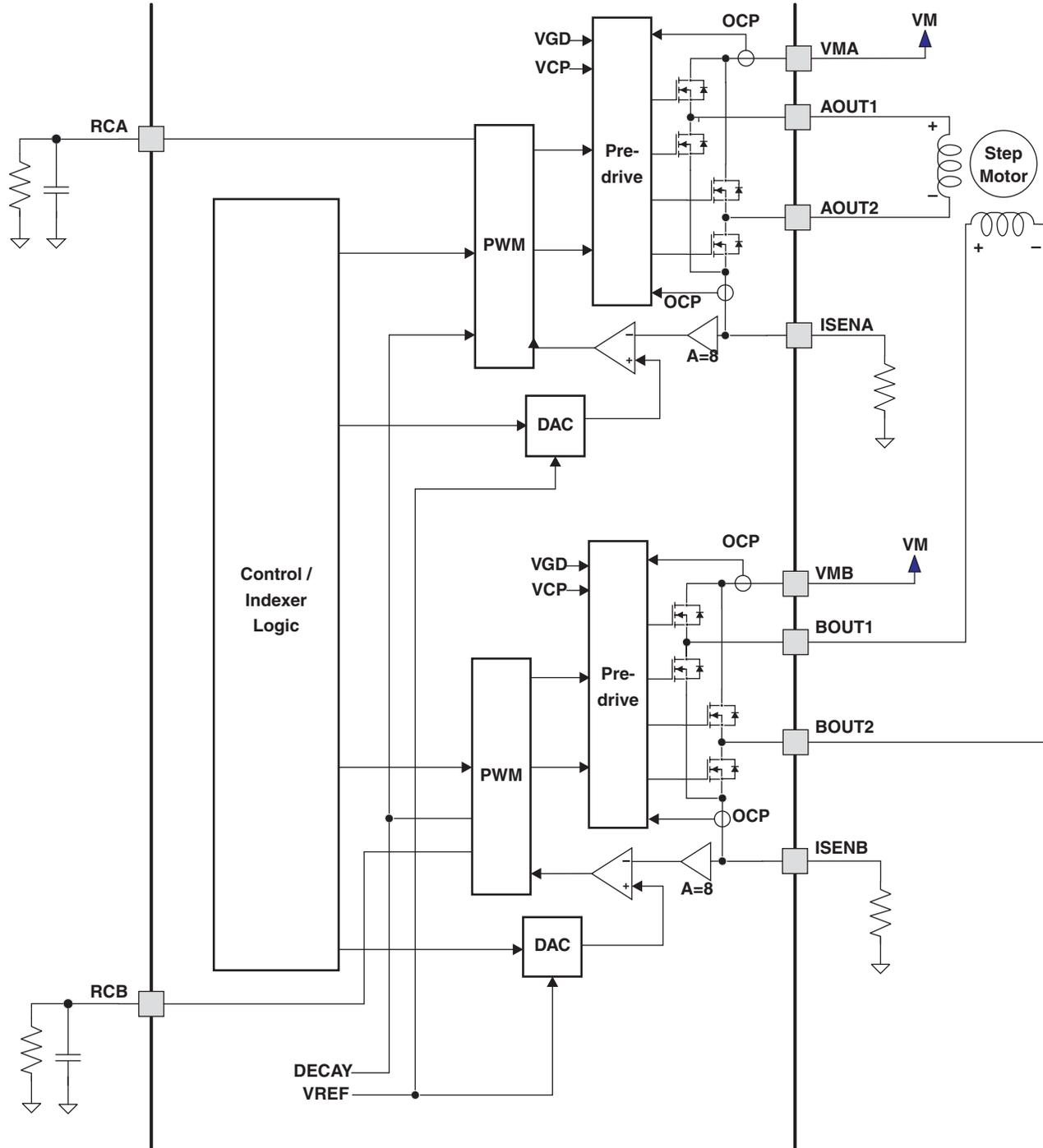


Figure 1. Block Diagram

Current Regulation

The PWM chopping current is set by a comparator, which compares the voltage across a current sense resistor, multiplied by a factor of 8, with a reference voltage. The reference voltage is input from the VREF pin. The full-scale (100%) chopping current is calculated as follows:

$$I_{CHOP} = \frac{V_{REFX}}{8 \cdot R_{ISENSE}} \quad (1)$$

Example:

If a 0.22-Ω sense resistor is used and the VREFx pin is 3.3 V, the full-scale (100%) chopping current is 3.3 V/(8 * 0.22 Ω) = 1.875 A.

The reference voltage is also scaled by an internal DAC that allows torque control for fractional stepping of a bipolar stepper motor, as described in the "Microstepping Indexer" section below.

When a winding is activated, the current through it rises until it reaches the chopping current threshold described above, then the current is switched off for a fixed off time. The off time is determined by the values of a resistor and capacitor connected to the RCA (for bridge A) and RCB (for bridge B) pins. The off time is approximated by:

$$t_{OFF} = R \cdot C \quad (2)$$

To avoid falsely tripping on transient currents when the winding is first activated, a blanking period is used immediately after turning on the FETs, during which the state of the current sense comparator is ignored. The blanking time is determined by the value of the capacitor connected to the RCx pin and is approximated by:

$$t_{BLANK} = 1400 \cdot C \quad (3)$$

Decay Mode

During PWM current chopping, the H-bridge is enabled to drive through the motor winding until the PWM current chopping threshold is reached. This is shown in [Figure 2](#), Item 1. The current flow direction shown indicates positive current flow in the step table below.

Once the chopping current threshold is reached, the H-bridge can operate in two different states, fast decay or slow decay.

In fast decay mode, once the PWM chopping current level has been reached, the H-bridge reverses state to allow winding current to flow in a reverse direction. If synchronous rectification is enabled (SRn pin logic low), the opposite FETs are turned on; as the winding current approaches zero, the bridge is disabled to prevent any reverse current flow. If SRn is high, current is recirculated through the body diodes, or through external Schottky diodes. Fast-decay mode is shown in [Figure 2](#), Item 2.

In slow-decay mode, winding current is re-circulated by enabling both of the low-side FETs in the bridge. This is shown in [Figure 2](#), Item 3.

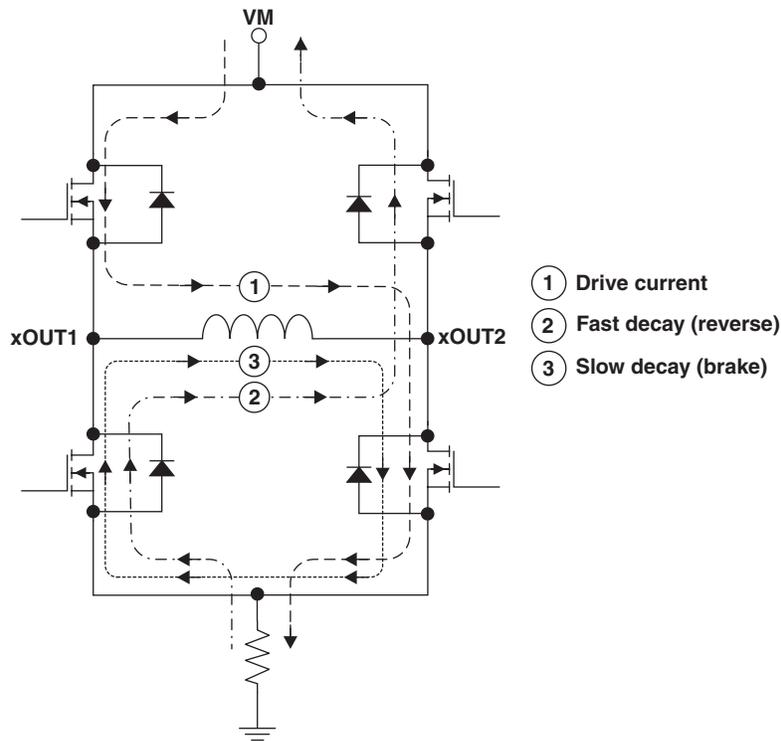


Figure 2. Decay Mode

The DRV8811 also supports a mixed decay mode. Mixed decay mode begins as fast decay, but after a period of time switches to slow decay mode for the remainder of the fixed off time.

Fast and mixed decay modes are only active if the current through the winding is decreasing; if the current is increasing, then slow decay is always used.

Which decay mode is used is selected by the voltage on the DECAY pin. If the voltage is greater than $0.6 \times V_{CC}$, slow decay mode is always used. If DECAY is less than $0.21 \times V_{CC}$, the device operates in fast decay mode when the current through the winding is decreasing. If the voltage is between these levels, mixed decay mode is enabled.

In mixed decay mode, the voltage on the DECAY pin sets the point in the cycle that the change to slow decay mode occurs. This time can be approximated by:

$$t_{FD} = R \cdot C \cdot \ln \left(\frac{0.6 \cdot V_{CC}}{V_{DECAY}} \right) \tag{4}$$

Operation of the blanking, fixed off time, and mixed decay mode is illustrated in [Figure 3](#).

FULL STEP USM = 00	1/2 STEP USM = 01	1/4 STEP USM = 10	1/8 STEP USM = 11	AOUTx CURRENT (% FULL-SCALE)	BOUTx CURRENT (% FULL-SCALE)	STEP ANGLE (DEGREES)
	1	1	1	100	0	0
			2	98	20	11.325
		2	3	92	38	22.5
			4	83	56	33.75
1	2	3	5	71	71	45 (home state)
			6	56	83	56.25
		4	7	38	92	67.5
			8	20	98	78.75
	3	5	9	0	100	90
			10	-20	98	101.25
		6	11	-38	92	112.5
			12	-56	83	123.75
2	4	7	13	-71	71	135
			14	-83	56	146.25
		8	15	-92	38	157.5
			16	-98	20	168.75
	5	9	17	-100	0	180
			18	-98	-20	191.25
		10	19	-92	-38	202.5
			20	-83	-56	213.75
3	6	11	21	-71	-71	225
			22	-56	-83	236.25
		12	23	-38	-92	247.5
			24	-20	-98	258.75
	7	13	25	0	-100	270
			26	20	-98	281.25
		14	27	38	-92	292.5
			28	56	-83	303.75
4	8	15	29	71	-71	315
			30	83	-56	326.25
		16	31	92	-38	337.5
			32	98	-20	348.75

RESETn, ENABLEn and SLEEPn Operation

The RESETn pin, when driven active low, resets the step table to the home position. It also disables the H-bridge drivers. The STEP input is ignored while RESETn is active.

The ENABLEn pin is used to control the output drivers. When ENABLEn is low, the output H-bridges are enabled. When ENABLEn is high, the H-bridges are disabled and the outputs are in a high-impedance state.

Note that when ENABLEn is high, the input pins and control logic, including the indexer (STEP and DIR pins) are still functional.

The SLEEPn pin is used to put the device into a low power state. If SLEEPn is low, the H-bridges are disabled, the gate drive charge pump is stopped, and all internal clocks are stopped. In this state all inputs are ignored until the SLEEPn pin returns high.

Protection Circuits

Overcurrent Protection (OCP)

If the current through any FET exceeds the preset overcurrent threshold, all FETs in the H-bridge will be disabled until the ENABLEn pin has been brought inactive high and then back low, or power is removed and re-applied. Overcurrent conditions are sensed in both directions; i.e., a short to ground, supply, or across the motor winding will all result in an overcurrent shutdown.

Note that overcurrent protection does not use the current sense circuitry used for PWM current control and is independent of the Isense resistor value or VREF voltage.

Thermal Shutdown (TSD)

If the die temperature exceeds safe limits, all drivers in the device are shut down and the indexer is reset to the home state. Once the die temperature has fallen to a safe level operation resumes.

Undervoltage Lockout (UVLO)

If at any time the voltage on the VM pins falls below the undervoltage lockout threshold voltage, all circuitry in the device is disabled and the indexer is reset to the home state. Operation resumes when VM rises above the UVLO threshold.

THERMAL INFORMATION

Thermal Protection

The DRV8811 has thermal shutdown (TSD) as described above. If the die temperature exceeds approximately 150°C, the device will be disabled until the temperature drops to a safe level.

Any tendency of the device to enter thermal shutdown is an indication of either excessive power dissipation, insufficient heatsinking, or too high an ambient temperature.

Power Dissipation

Power dissipation in the DRV8811 is dominated by the power dissipated in the output FET resistance, or $R_{DS(ON)}$. Average power dissipation when running a stepper motor can be roughly estimated by:

$$P_{TOT} = 4 \cdot R_{DS(ON)} \cdot (I_{OUT(RMS)})^2 \quad (5)$$

where P_{TOT} is the total power dissipation, $R_{DS(ON)}$ is the resistance of each FET, and $I_{OUT(RMS)}$ is the RMS output current being applied to each winding. $I_{OUT(RMS)}$ is equal to the approximately 0.7x the full-scale output current setting. The factor of 4 comes from the fact that there are two motor windings, and at any instant two FETs are conducting winding current for each winding (one high-side and one low-side).

The maximum amount of power that can be dissipated in the DRV8811 is dependent on ambient temperature and heatsinking. [Figure 4](#) and [Figure 5](#) show how the maximum allowable power dissipation varies according to temperature and PCB construction. [Figure 4](#) shows data for a JEDEC low-K board, 2-layers with 2-oz. copper, 76 mm x 114 mm x 1.6 mm thick, with either no backside copper or a 24 cm² copper area on the backside. Similarly, [Figure 5](#) shows data for a JEDEC high-K board, 4 layers with 1-oz. copper, 76 mm x 114 mm x 1.6 mm thick, and a solid internal ground plane. In this case, the PowerPAD™ is tied to the ground plane using thermal vias, and no additional outer layer copper.

Note that $R_{DS(ON)}$ increases with temperature, so as the device heats, the power dissipation increases. This must be taken into consideration when sizing the heatsink. Refer to [Figure 6](#).

Heatsinking

The PowerPAD™ package uses an exposed pad to remove heat from the device. For proper operation, this pad must be thermally connected to copper on the PCB to dissipate heat. On a multi-layer PCB with a ground plane, this can be accomplished by adding a number of vias to connect the thermal pad to the ground plane. On PCBs without internal planes, copper area can be added on either side of the PCB to dissipate heat. If the copper area is on the opposite side of the PCB from the device, thermal vias are used to transfer the heat between top and bottom layers.

For details about how to design the PCB, refer to TI Application Report [SLMA002](#), "PowerPAD™ Thermally Enhanced Package" and TI Application Brief [SLMA004](#), "PowerPAD™ Made Easy", available at www.ti.com.

In general, the more copper area that can be provided, the more power can be dissipated. [Figure 7](#) shows thermal resistance vs. copper plane area for a single-sided PCB with 2-oz. copper heatsink area. It can be seen that the heatsink effectiveness increases rapidly to about 20 cm², then levels off somewhat for larger areas.

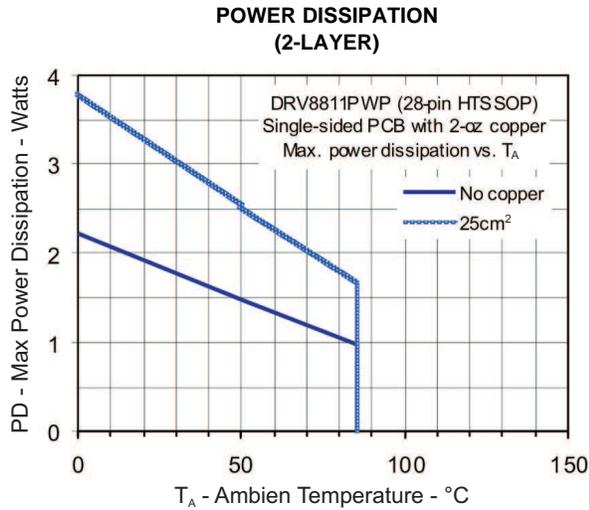


Figure 4.

**TYPICAL $R_{DS(ON)}$
vs
TEMPERATURE**

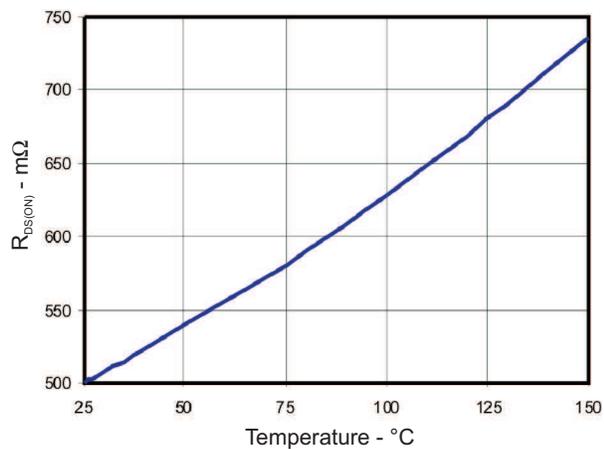


Figure 6.

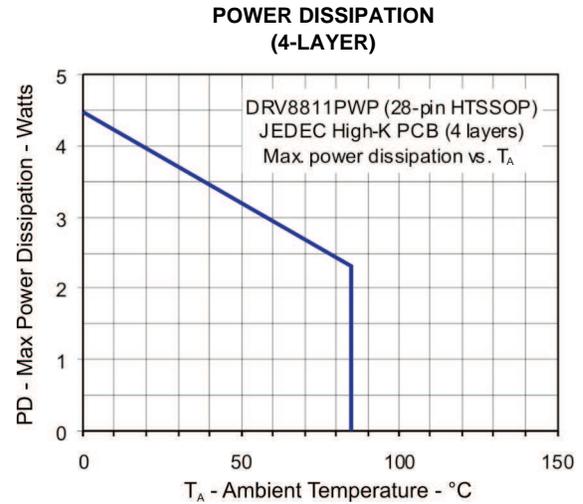


Figure 5.

**THERMAL RESISTANCE
vs
COPPER AREA**

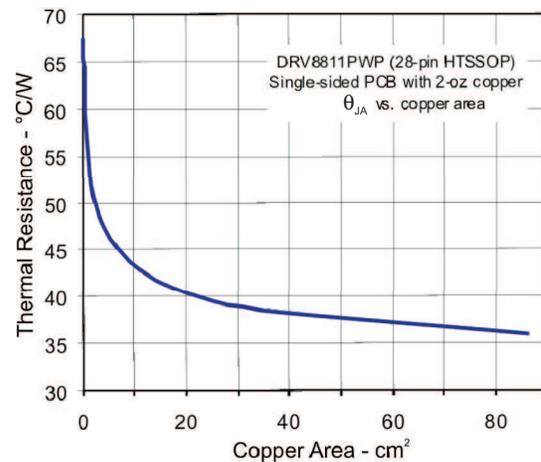


Figure 7.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
DRV8811PWP	ACTIVE	HTSSOP	PWP	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
DRV8811PWPR	ACTIVE	HTSSOP	PWP	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

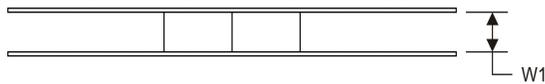
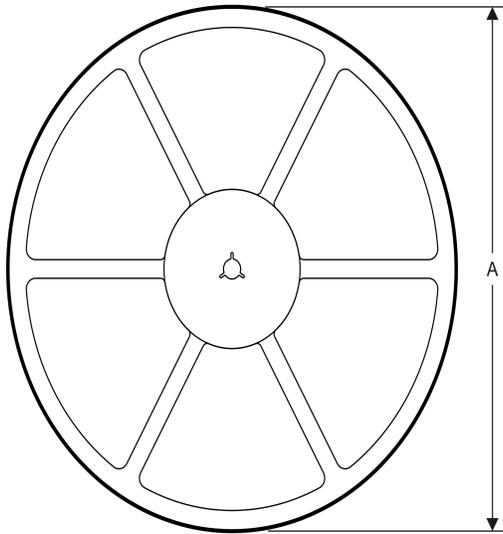
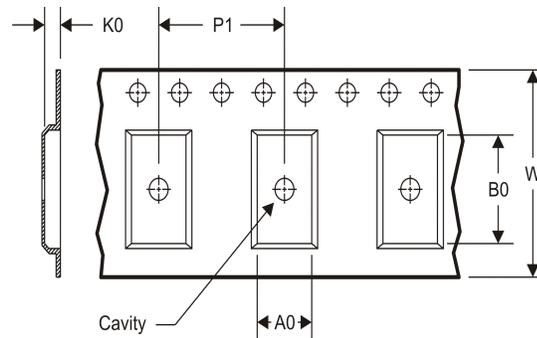
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


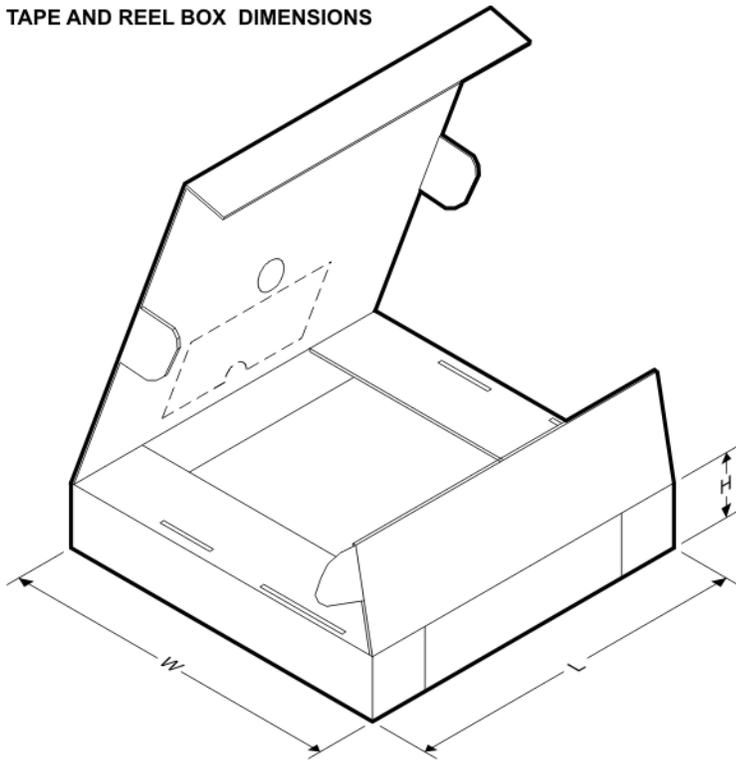
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DRV8811PWPR	HTSSOP	PWP	28	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



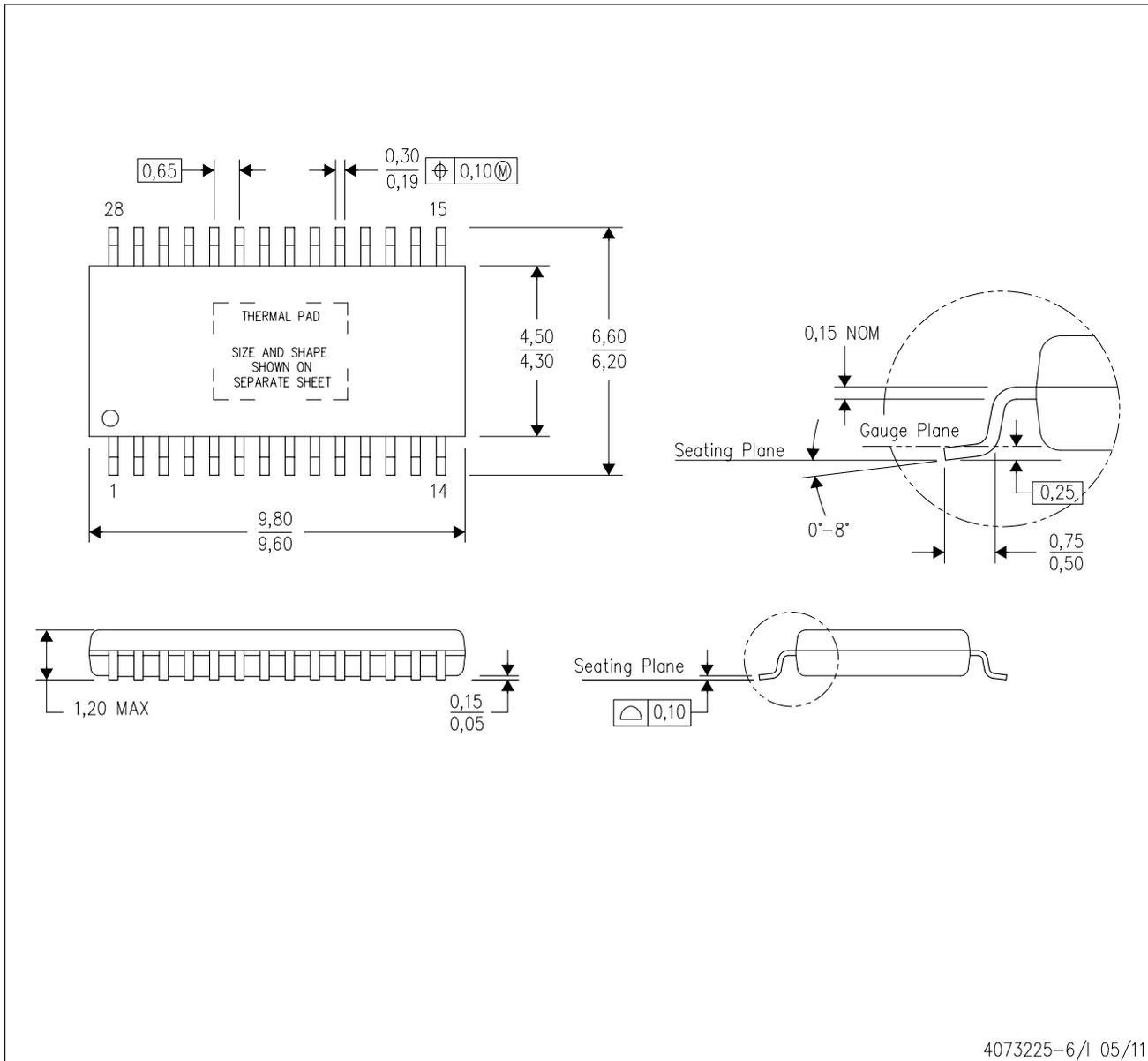
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DRV8811PWPR	HTSSOP	PWP	28	2000	367.0	367.0	38.0

MECHANICAL DATA

PWP (R-PDSO-G28)

PowerPAD™ PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.15 per side.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <<http://www.ti.com>>.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - Falls within JEDEC MO-153

PowerPAD is a trademark of Texas Instruments.

THERMAL PAD MECHANICAL DATA

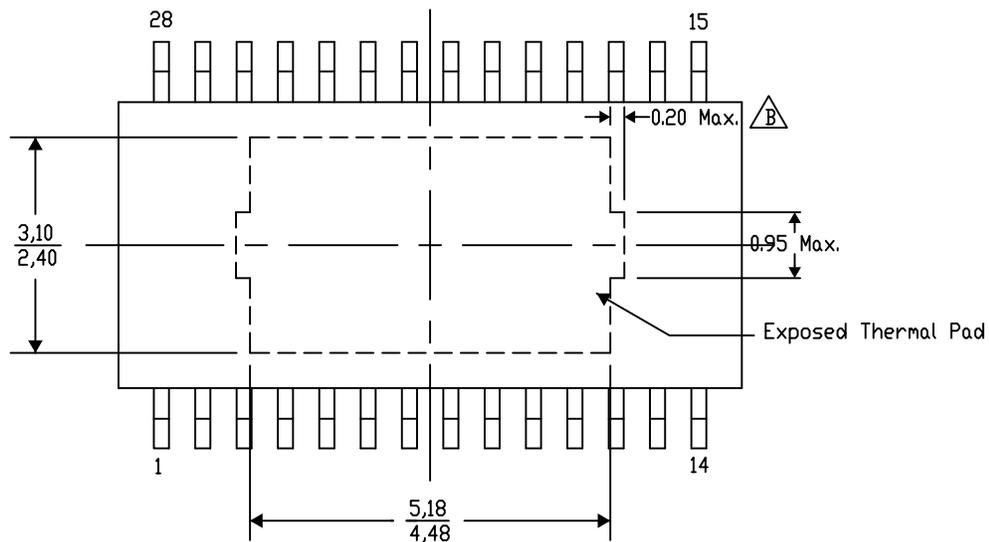
PWP (R-PDSO-G28) PowerPAD™ SMALL PLASTIC OUTLINE

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Exposed Thermal Pad Dimensions

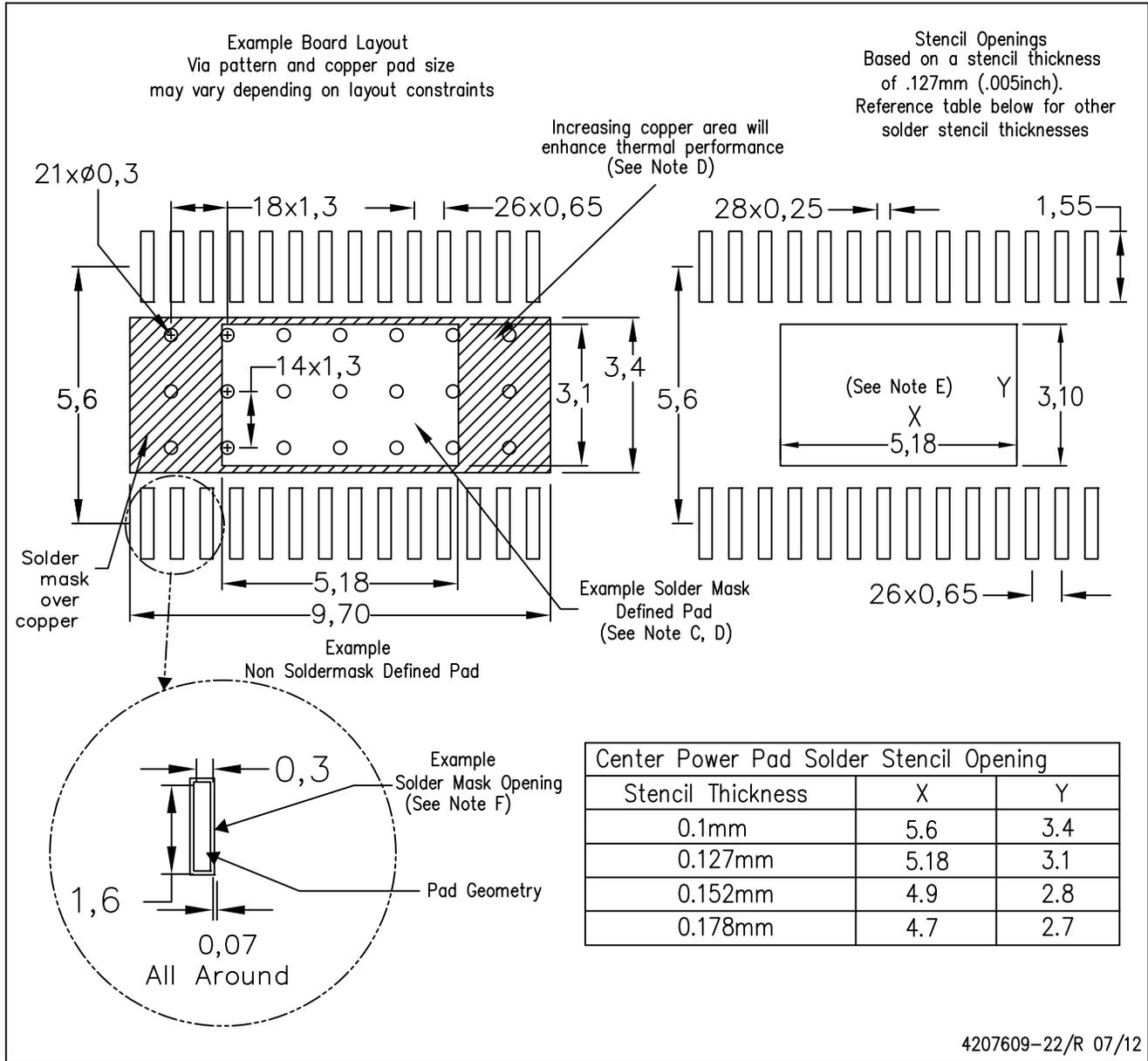
4206332-38/AC 07/12

NOTE: A. All linear dimensions are in millimeters
B. Exposed tie strap features may not be present.

PowerPAD is a trademark of Texas Instruments

PWP (R-PDSO-G28)

PowerPAD™ PLASTIC SMALL OUTLINE



4207609-22/R 07/12

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets.
 - For specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>. Publication IPC-7351 is recommended for alternate designs. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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